



<b>PCN Number:</b>	20150219001	<b>PCN Date:</b>	2/24/2015
<b>Title:</b>	Qualification of TI Mexico as a new Assembly and Test site for select PIP Module Devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	05/24/2015	<b>Estimated Sample Availability:</b>	Provided upon Request
<b>Change Type:</b>			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
<input type="checkbox"/>		<input type="checkbox"/>	Part number change
<b>PCN Details</b>			
<b>Description of Change:</b>			
<p>Texas Instruments is pleased to announce the qualification of TI Mexico as a new Assembly and test site for the list of PIP devices shown below. There are no differences in the package construction as a result of this change.</p> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>			
<b>Reason for Change:</b>			
Continuity of Supply			
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>			
None			

<b>Changes to product identification resulting from this PCN:</b>		
Assembly Site		
Hana Thailand	Assembly Site Origin (22L)	ASO: HNT
<b>TI Mexico</b>	Assembly Site Origin (22L)	ASO: <b>PTM</b>
Sample product shipping label (not actual product label)		
 MADE IN: Malaysia 2DC: 20: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 <b>LBL: 5A (L)TO:1750</b>		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: <u>MLA</u> (23L) ACO: MYS
<b>Topside Device marking:</b>		
Assembly site code for HNT= H		
<b>Assembly site code for MEX= V</b>		

<b>Product Affected</b>			
PTR08060WVC	PTR08060WVD	PTR08100WVC	PTR08100WVD

### Qualification Data: Approved February 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

#### Qualification Device: PTR08100WVD

#### Package Construction Details

<b>Assembly Site:</b>	FMX A/T	<b>Lead Finish:</b>	Matte Sn
<b># Pins-Designator, Family:</b>	5-EDN, SIP MODULE		

**Qualification:**  Plan  Test Results

Reliability Test	Conditions	Sample Size/Fail	
		Lot#1	Lot#2
Biased Power Cycled Life	45.6C Case Temp, 1000 Hrs	40/0	--
Biased Humidity	85C/85%RH, 1000 Hrs	40/0	--
Vibration	MIL-STD-883D, 2007.2	9/0	9/0
Mechanical Shock	MIL-STD-883D, 2007.3	3/0	3/0

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>